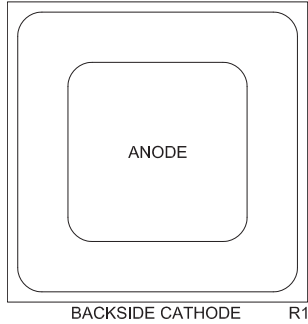


CPD69-1N4003

General Purpose Rectifier Die

1.0 Amp, 200 Volt

The CPD69-1N4003 is a silicon 1.0 Amp, 200 Volt general purpose rectifier ideal for all types of commercial, industrial, entertainment, and computer applications.



MECHANICAL SPECIFICATIONS:

| | |
|------------------------|-----------------------|
| Die Size | 42.5 x 42.5 MILS |
| Die Thickness | 11.0 MILS |
| Anode Bonding Pad Size | 24 x 24 MILS |
| Top Side Metalization | Ni/Au – 5,000Å/1,350Å |
| Back Side Metalization | Ni/Au – 5,000Å/1,350Å |
| Scribe Alley Width | 2.76 MILS |
| Wafer Diameter | 4 INCHES |
| Gross Die Per Wafer | 5,915 |

MAXIMUM RATINGS: ($T_A=25^\circ\text{C}$)

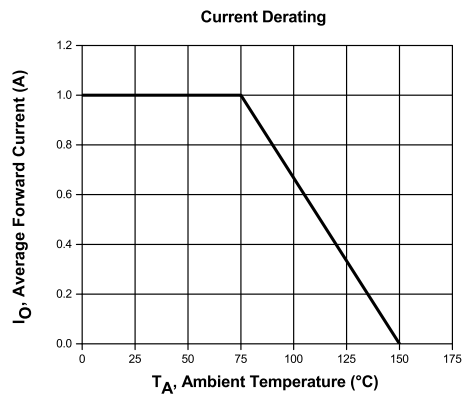
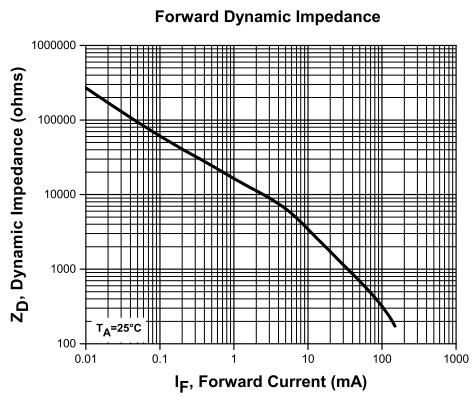
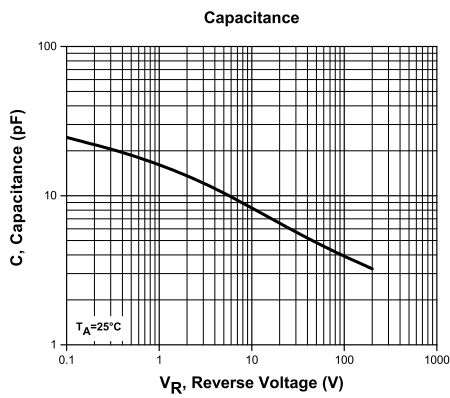
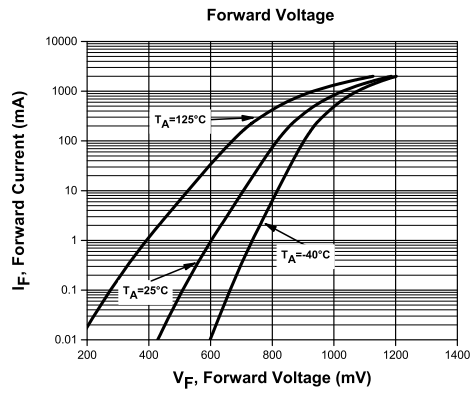
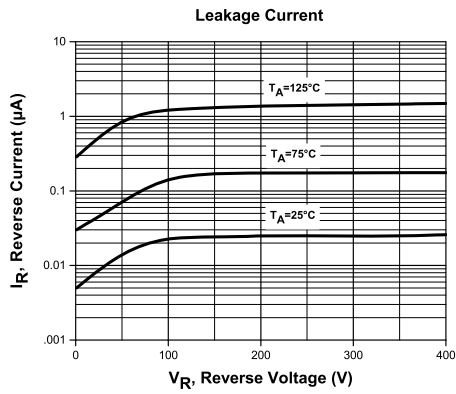
| | SYMBOL | | UNITS |
|--|----------------|-------------|------------------|
| Peak Repetitive Reverse Voltage | V_{RRM} | 200 | V |
| DC Blocking Voltage | V_R | 200 | V |
| RMS Reverse Voltage | $V_{R(RMS)}$ | 140 | V |
| Average Forward Current ($T_A=75^\circ\text{C}$) | I_O | 1.0 | A |
| Peak Forward Surge Current, $t_p=8.3\text{ms}$ | I_{FSM} | 50 | A |
| Operating and Storage Junction Temperature | T_J, T_{stg} | -65 to +150 | $^\circ\text{C}$ |

ELECTRICAL CHARACTERISTICS: ($T_A=25^\circ\text{C}$ unless otherwise)

| SYMBOL | TEST CONDITIONS | MIN | MAX | UNITS |
|--------|--------------------------|-----|-----|---------------|
| I_R | $V_R=200\text{V}$ | | 5.0 | μA |
| V_F | $I_F=1.0\text{A}$ | | 1.1 | V |
| C_J | $V_R=0, f=1.0\text{MHz}$ | | 40 | pF |

CPD69-1N4003

Typical Electrical Characteristics



BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

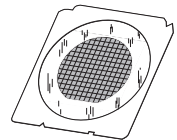
WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp.
145 Adams Avenue
Hauppauge, NY 11788 USA
Main Tel: (631) 435-1110
Main Fax: (631) 435-1824
Support Team Fax: (631) 435-3388
www.centrasemi.com

Worldwide Field Representatives:
www.centrasemi.com/wwreps

Worldwide Distributors:
www.centrasemi.com/wwdistributors

For the latest version of Central Semiconductor's **LIMITATIONS AND DAMAGES DISCLAIMER**, which is part of Central's Standard Terms and Conditions of sale, visit: www.centrasemi.com/terms